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(54) **LAMINATE FOR WIRING BOARD**

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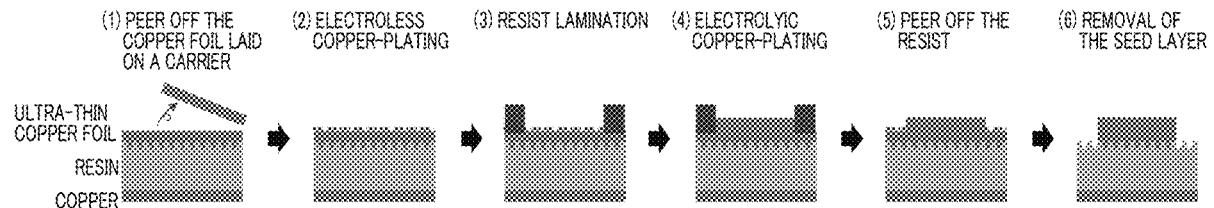
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ABSTRACT

The present invention is directed to provide novel laminates for wiring boards. Novel laminates for wiring boards according to the present invention includes an insulating substrate layer and copper wiring, the laminate having a circuit linearity of 1.0 or more and 1.7 or less.

(A)

(A-1)



(A-2)

